eman ta zabal zazu

BILBOKO INDUSTRIA INGENIARITZA TEKNIKOKO UNIBERTSITATE ESKOLA

INDUSTRIA ELEKTRONIKAREN ETA AUTOMATIKAREN INGENIARITZAKO GRADUA

GRADU AMAIERAKO LANA

2013 / 2014

IZPI INFRAGORRIZ KONTROLATUTAKO PLATAFORMA MUGIKORRA

5.ERANSKINAK

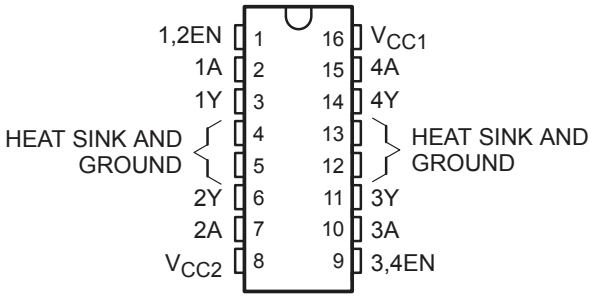
IKASLEAREN DATUAK	**ZUZENDARIAREN DATUAK**
IZENA: ANDER	IZENA: OSKAR
ABIZENAK: ELEZKANO BILBAO	ABIZENAK: CASQUERO OYARZABAL
	SAILA: AUTOMATIKA ETA SISTEMEN INGENIARITZA
SIN.:	SIN.:
DATA:	DATA:

L293, L293D
QUADRUPLE HALF-H DRIVERS

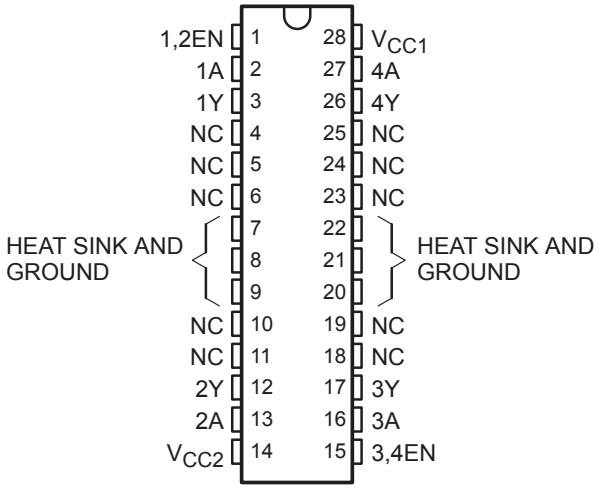
SLRS008C − SEPTEMBER 1986 − REVISED NOVEMBER 2004

- **Featuring Unitrode L293 and L293D Products Now From Texas Instruments**
- **Wide Supply-Voltage Range: 4.5 V to 36 V**
- **Separate Input-Logic Supply**
- **Internal ESD Protection**
- **Thermal Shutdown**
- **High-Noise-Immunity Inputs**
- **Functionally Similar to SGS L293 and SGS L293D**
- **Output Current 1 A Per Channel (600 mA for L293D)**
- **Peak Output Current 2 A Per Channel (1.2 A for L293D)**
- **Output Clamp Diodes for Inductive Transient Suppression (L293D)**

L293 . . . N OR NE PACKAGE
L293D . . . NE PACKAGE
(TOP VIEW)



L293 . . . DWP PACKAGE
(TOP VIEW)



description/ordering information

The L293 and L293D are quadruple high-current half-H drivers. The L293 is designed to provide bidirectional drive currents of up to 1 A at voltages from 4.5 V to 36 V. The L293D is designed to provide bidirectional drive currents of up to 600-mA at voltages from 4.5 V to 36 V. Both devices are designed to drive inductive loads such as relays, solenoids, dc and bipolar stepping motors, as well as other high-current/high-voltage loads in positive-supply applications.

All inputs are TTL compatible. Each output is a complete totem-pole drive circuit, with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs, with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN. When an enable input is high, the associated drivers are enabled, and their outputs are active and in phase with their inputs. When the enable input is low, those drivers are disabled, and their outputs are off and in the high-impedance state. With the proper data inputs, each pair of drivers forms a full-H (or bridge) reversible drive suitable for solenoid or motor applications.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	HSOP (DWP)	Tube of 20	L293DWP	L293DWP
	PDIP (N)	Tube of 25	L293N	L293N
	PDIP (NE)	Tube of 25	L293NE	L293NE
		Tube of 25	L293DNE	L293DNE

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

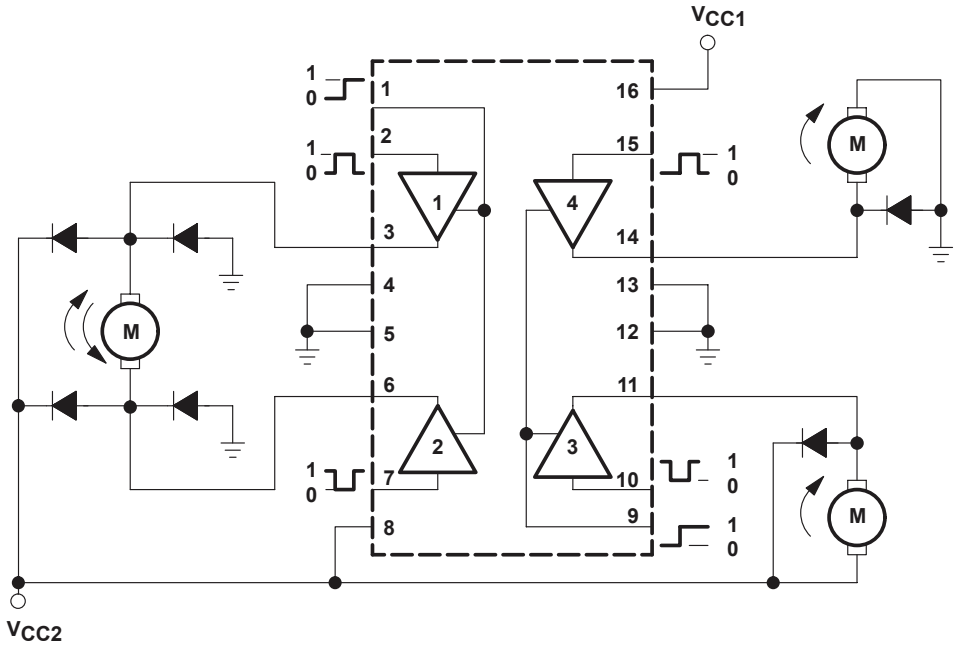
description/ordering information (continued)

On the L293, external high-speed output clamp diodes should be used for inductive transient suppression.

A V_{CC1} terminal, separate from V_{CC2}, is provided for the logic inputs to minimize device power dissipation.

The L293and L293D are characterized for operation from 0°C to 70°C.

block diagram



NOTE: Output diodes are internal in L293D.

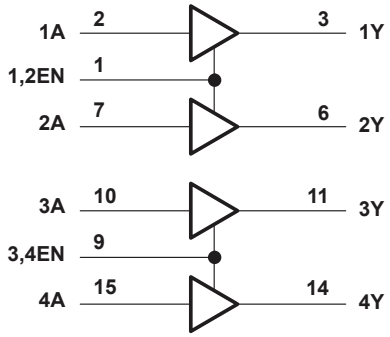
FUNCTION TABLE
(each driver)

INPUTS†		OUTPUT
A	EN	Y
H	H	H
L	H	L
X	L	Z

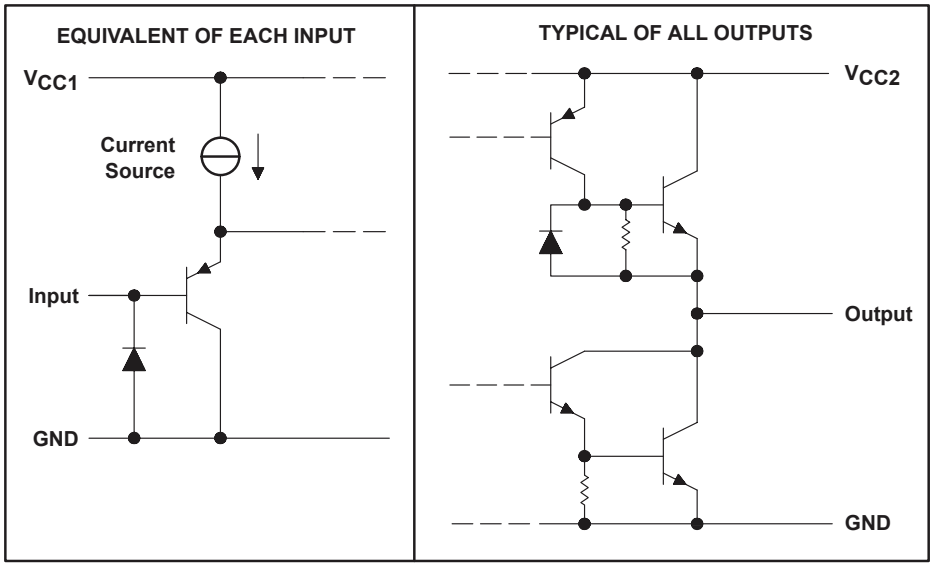
H = high level, L = low level, X = irrelevant,
Z = high impedance (off)

† In the thermal shutdown mode, the output is in the high-impedance state, regardless of the input levels.

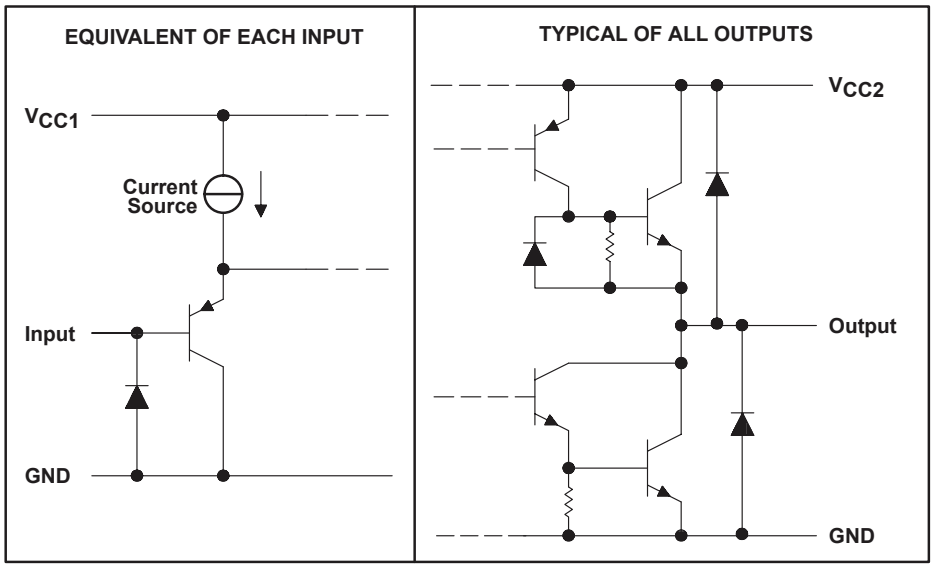
logic diagram



schematics of inputs and outputs (L293)



schematics of inputs and outputs (L293D)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC1} (see Note 1)	36 V
Output supply voltage, V_{CC2}	36 V
Input voltage, V_I	7 V
Output voltage range, V_O	−3 V to V_{CC2} + 3 V
Peak output current, I_O (nonrepetitive, t ≤ 5 ms): L293	±2 A
Peak output current, I_O (nonrepetitive, t ≤ 100 μs): L293D	±1.2 A
Continuous output current, I_O: L293	±1 A
Continuous output current, I_O: L293D	±600 mA
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DWP package	TBD°C/W
N package	67°C/W
NE package	TBD°C/W
Maximum junction temperature, T_J	150°C
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to the network ground terminal.
2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	MAX	UNIT
	Supply voltage	V_{CC1}	4.5	7	V
		V_{CC2}	V_{CC1}	36	
V_{IH}	High-level input voltage	$V_{CC1} \le 7$ V	2.3	V_{CC1}	V
		$V_{CC1} \ge 7$ V	2.3	7	V
V_{IL}	Low-level output voltage		−0.3†	1.5	V
T_A	Operating free-air temperature		0	70	°C

† The algebraic convention, in which the least positive (most negative) designated minimum, is used in this data sheet for logic voltage levels.

electrical characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

PARAMETER			TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage		L293: I_{OH} = −1 A L293D: I_{OH} = −0.6 A		V_{CC2} − 1.8	V_{CC2} − 1.4		V
V_{OL}	Low-level output voltage		L293: I_{OL} = 1 A L293D: I_{OL} = 0.6 A			1.2	1.8	V
V_{OKH}	High-level output clamp voltage		L293D: I_{OK} = −0.6 A			V_{CC2} + 1.3		V
V_{OKL}	Low-level output clamp voltage		L293D: I_{OK} = 0.6 A			1.3		V
I_{IH}	High-level input current	A	V_I = 7 V			0.2	100	µA
		EN				0.2	10	
I_{IL}	Low-level input current	A	V_I = 0			−3	−10	µA
		EN				−2	−100	
I_{CC1}	Logic supply current		I_O = 0	All outputs at high level		13	22	mA
				All outputs at low level		35	60	
				All outputs at high impedance		8	24	
I_{CC2}	Output supply current		I_O = 0	All outputs at high level		14	24	mA
				All outputs at low level		2	6	
				All outputs at high impedance		2	4	

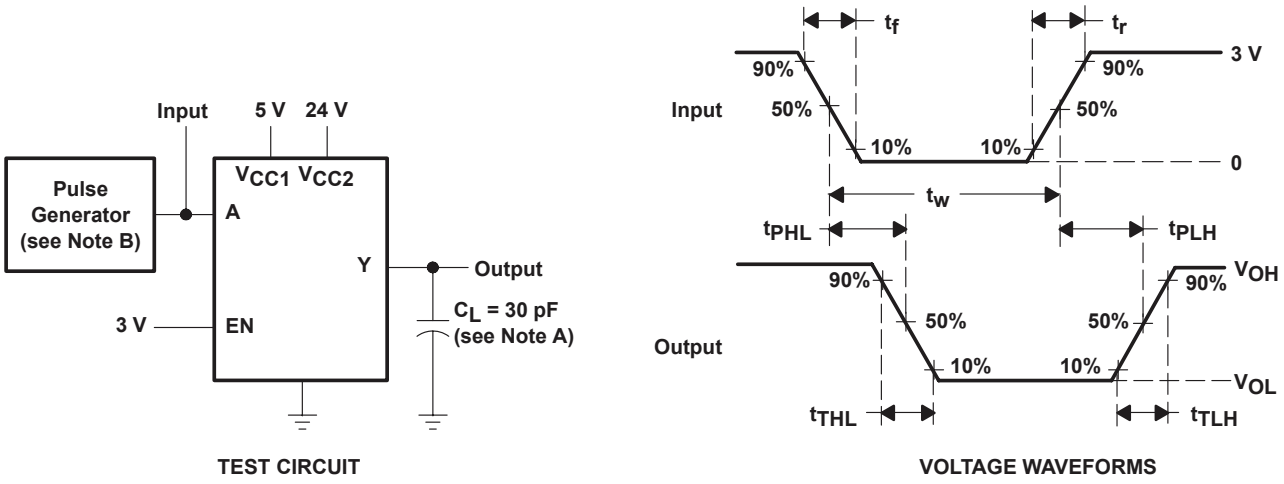
switching characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	L293NE, L293DNE			UNIT
			MIN	TYP	MAX	
t_{PLH}	Propagation delay time, low-to-high-level output from A input	C_L = 30 pF, See Figure 1		800		ns
t_{PHL}	Propagation delay time, high-to-low-level output from A input			400		ns
t_{TLH}	Transition time, low-to-high-level output			300		ns
t_{THL}	Transition time, high-to-low-level output			300		ns

switching characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	L293DWP, L293N L293DN			UNIT
			MIN	TYP	MAX	
t_{PLH}	Propagation delay time, low-to-high-level output from A input	C_L = 30 pF, See Figure 1		750		ns
t_{PHL}	Propagation delay time, high-to-low-level output from A input			200		ns
t_{TLH}	Transition time, low-to-high-level output			100		ns
t_{THL}	Transition time, high-to-low-level output			350		ns

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: $t_r \le 10$ ns, $t_f \le 10$ ns, $t_w = 10$ µs, PRR = 5 kHz, $Z_O = 50\ \Omega$.

Figure 1. Test Circuit and Voltage Waveforms

APPLICATION INFORMATION

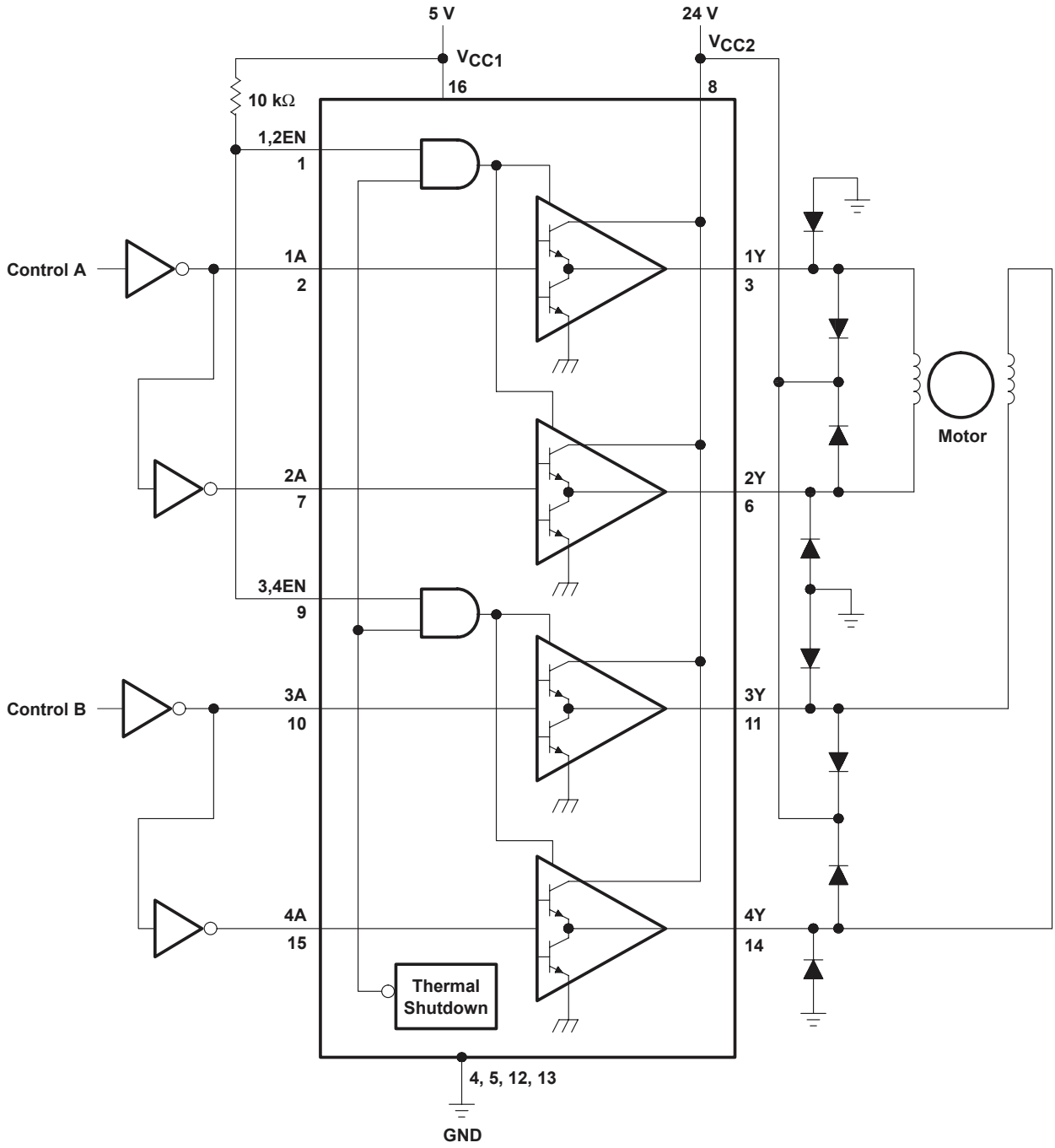


Figure 2. Two-Phase Motor Driver (L293)

APPLICATION INFORMATION

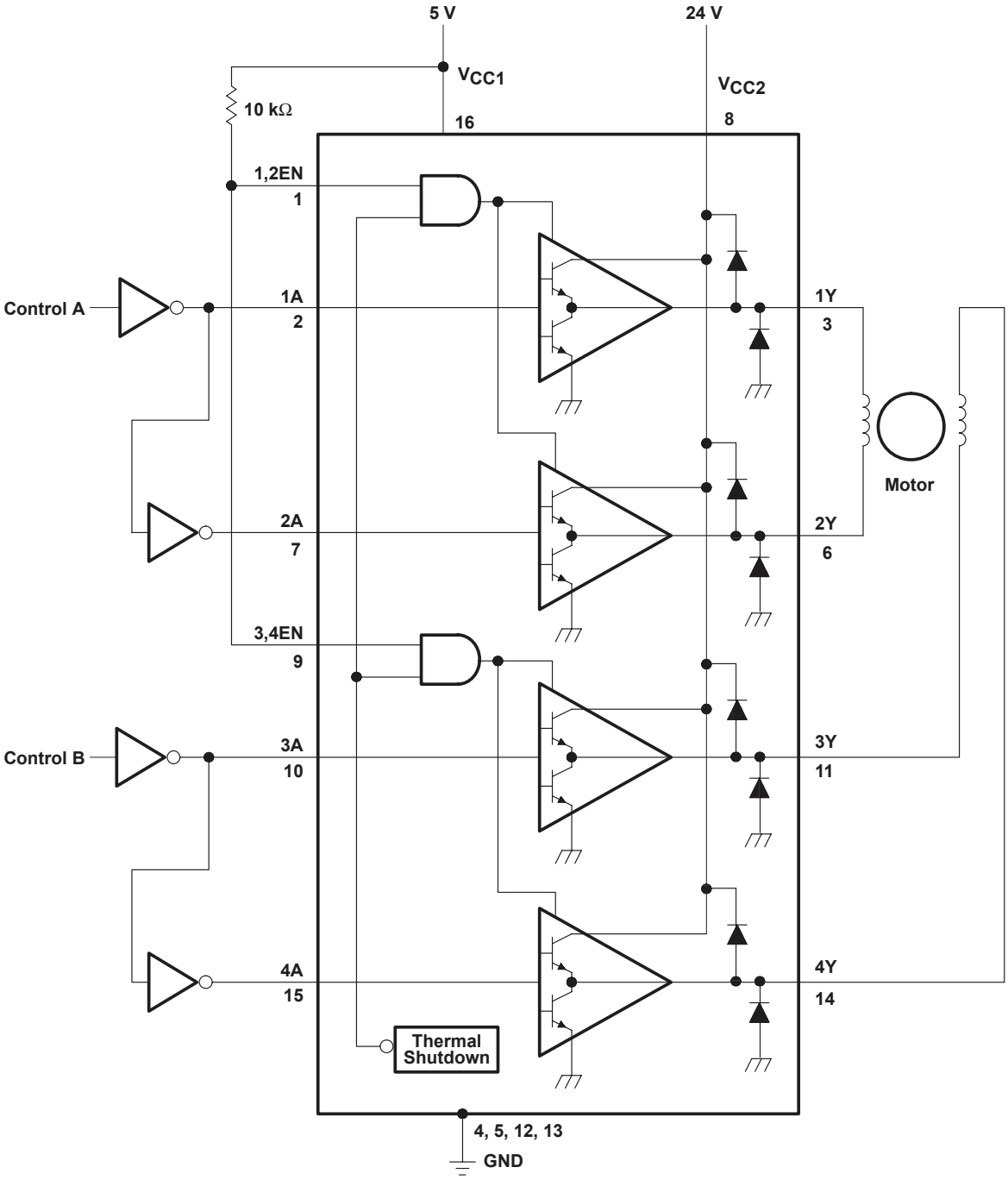


Figure 3. Two-Phase Motor Driver (L293D)

APPLICATION INFORMATION

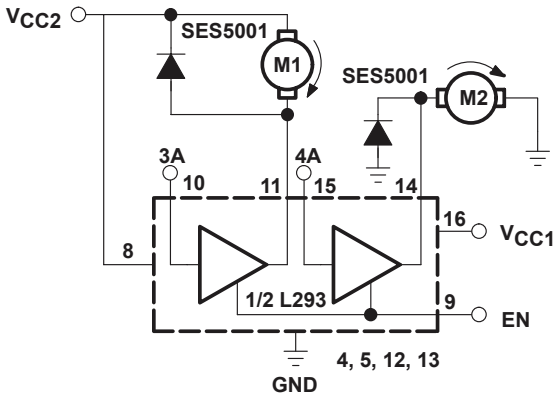


Figure 4. DC Motor Controls (connections to ground and to supply voltage)

EN	3A	M1	4A	M2
H	H	Fast motor stop	H	Run
H	L	Run	L	Fast motor stop
L	X	Free-running motor stop	X	Free-running motor stop

L = low, H = high, X = don't care

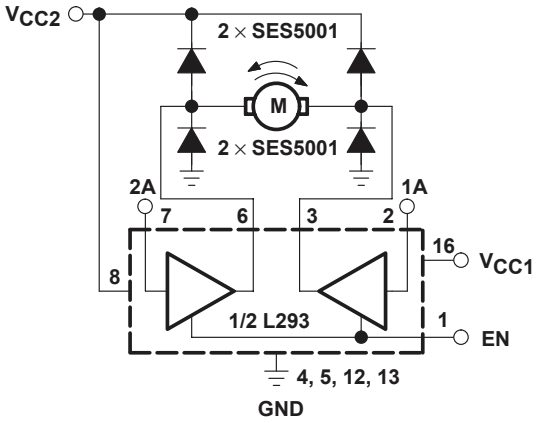
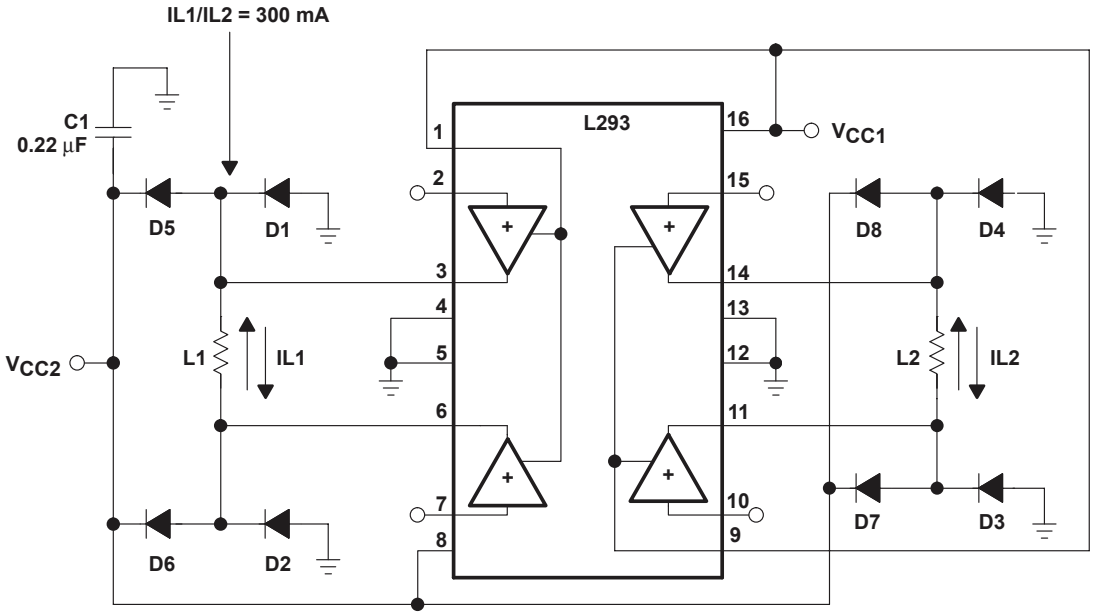


Figure 5. Bidirectional DC Motor Control

EN	1A	2A	FUNCTION
H	L	H	Turn right
H	H	L	Turn left
H	L	L	Fast motor stop
H	H	H	Fast motor stop
L	X	X	Fast motor stop

L = low, H = high, X = don't care

APPLICATION INFORMATION



D1−D8 = SES5001

Figure 6. Bipolar Stepping-Motor Control

mounting instructions

The Rthj-amp of the L293 can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board or to an external heat sink.

Figure 9 shows the maximum package power P_{TOT} and the θ_{JA} as a function of the side ℓ of two equal square copper areas having a thickness of 35 μm (see Figure 7). In addition, an external heat sink can be used (see Figure 8).

During soldering, the pin temperature must not exceed 260°C, and the soldering time must not exceed 12 seconds.

The external heatsink or printed circuit copper area must be connected to electrical ground.

APPLICATION INFORMATION

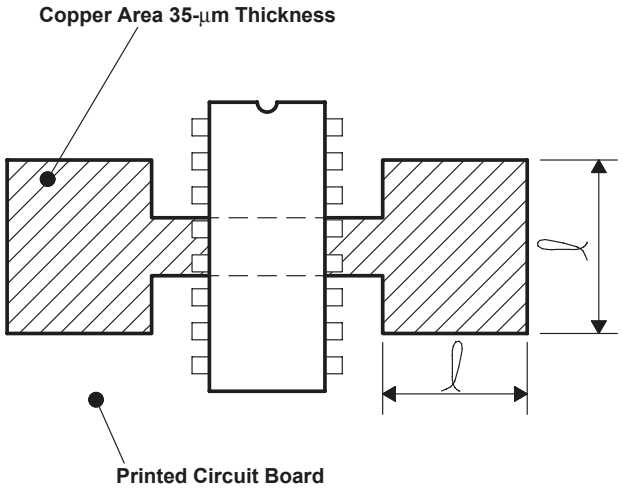


Figure 7. Example of Printed Circuit Board Copper Area (used as heat sink)

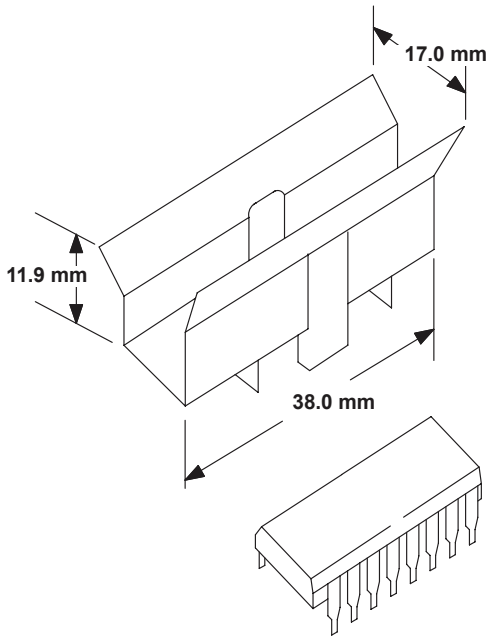


Figure 8. External Heat Sink Mounting Example (θ_{JA} = 25°C/W)

APPLICATION INFORMATION

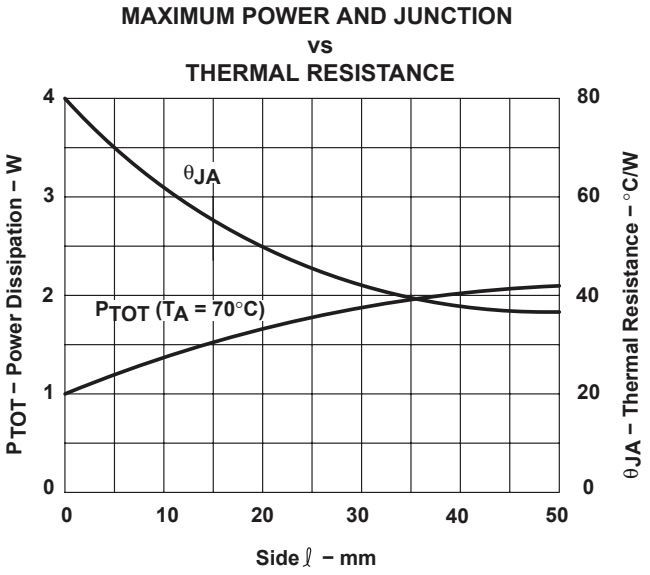


Figure 9

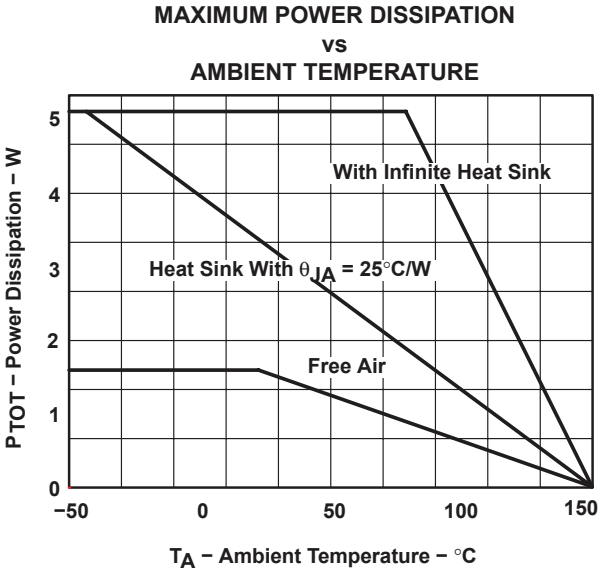


Figure 10

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
L293DDWP	OBSOLETE	SOIC	DW	28		None	CU SNPB	Level-2-220C-1 YEAR
L293DDWPTR	OBSOLETE	SOIC	DW	28		None	CU SNPB	Level-2-220C-1 YEAR
L293DN	OBSOLETE	PDIP	N	16		None	CU SNPB	Level-NA-NA-NA
L293DNE	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	Call TI	Level-NC-NC-NC
L293DSP	OBSOLETE			16		None	Call TI	Call TI
L293DSP883B	OBSOLETE			16		None	Call TI	Call TI
L293DSP883C	OBSOLETE		UTR			None	Call TI	Call TI
L293DWP	ACTIVE	SO Power PAD	DWP	28	20	None	Call TI	Level-2-220C-1 YEAR
L293DWPTR	OBSOLETE	SO Power PAD	DWP	28		None	Call TI	Call TI
L293N	ACTIVE	PDIP	N	16	25	None	CU SNPB	Level-NA-NA-NA
L293NE	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

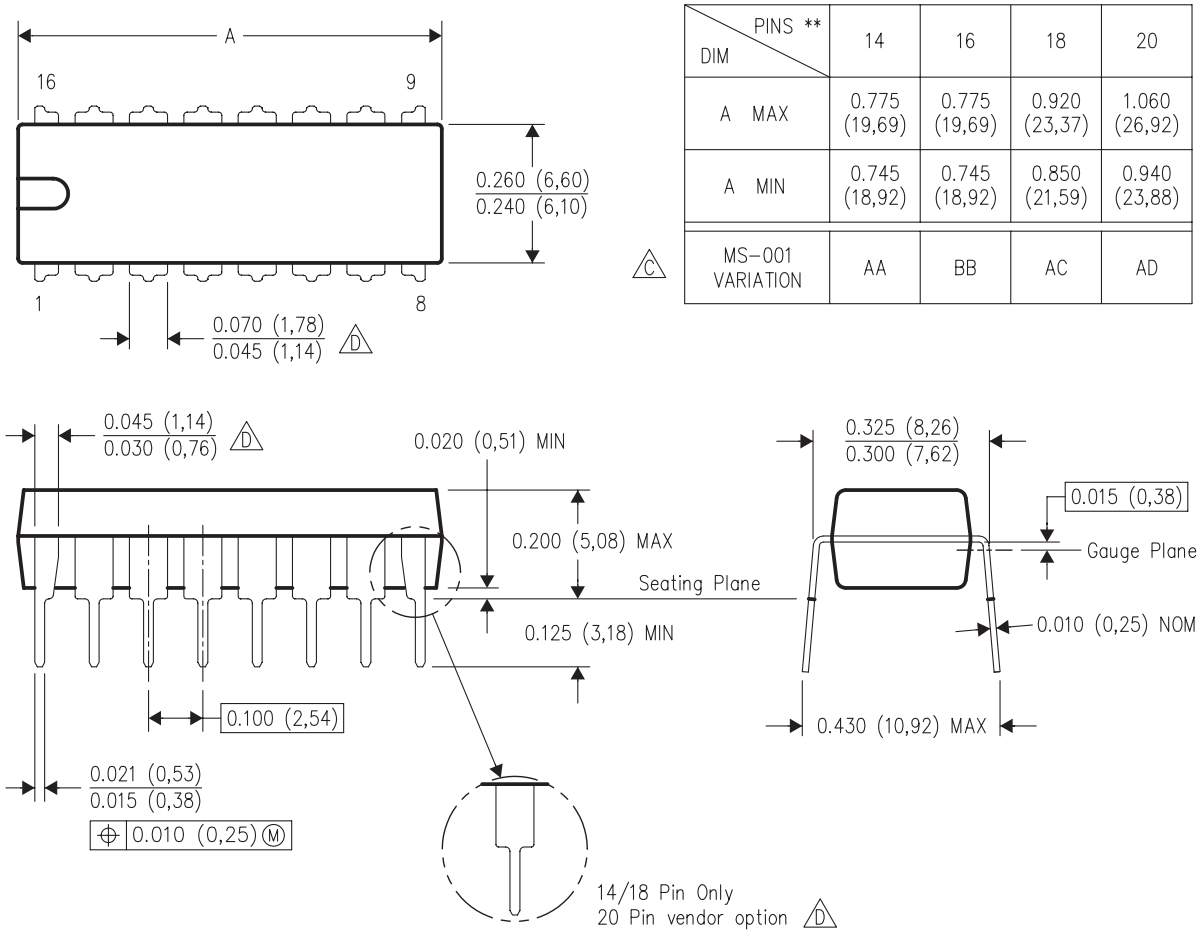
(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
None: Not yet available Lead (Pb-Free).
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION	AA	BB	AC	AD

C

4040049/E 12/2002

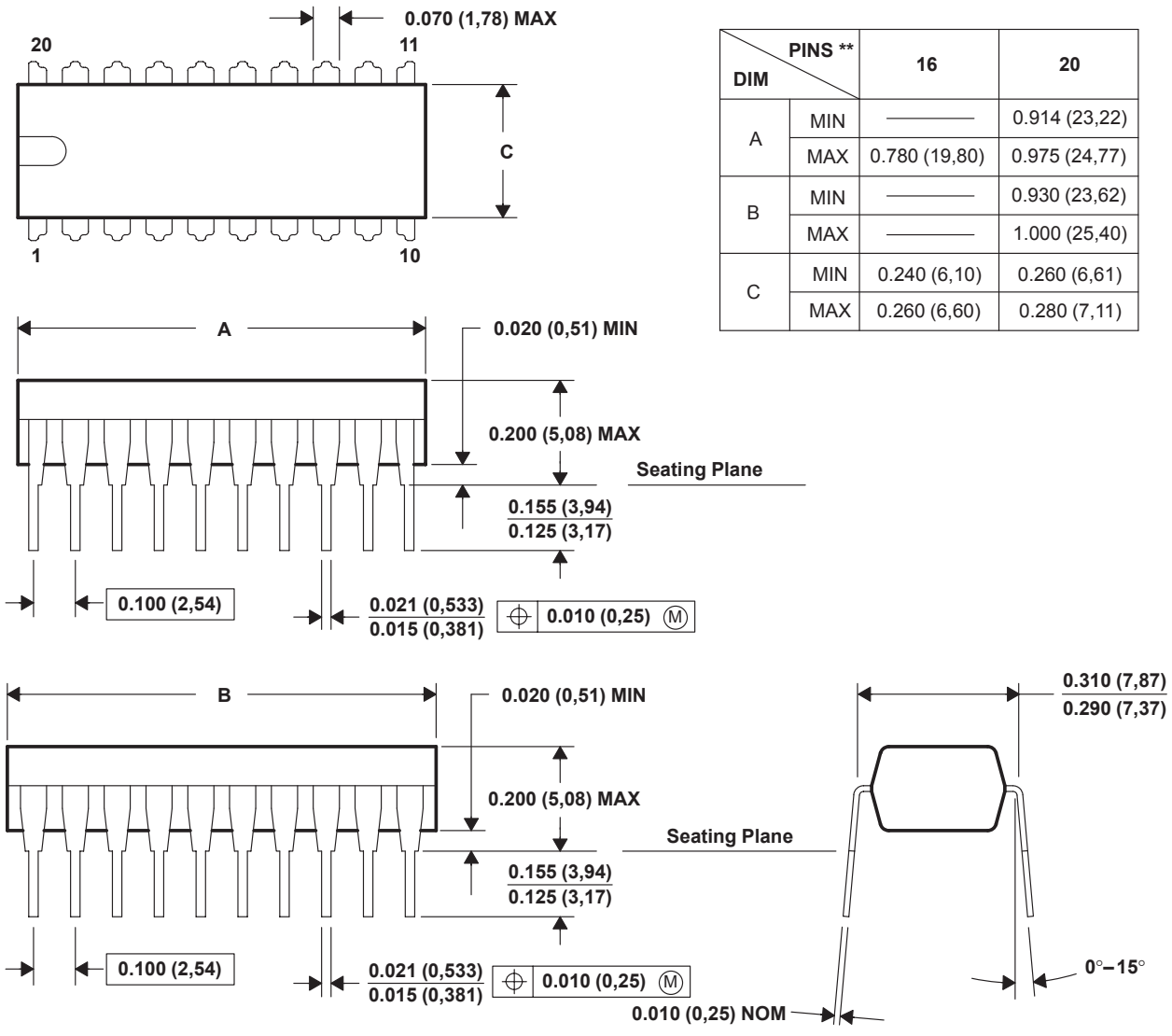
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

MPDI003 – OCTOBER 1994

NE (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

20 PIN SHOWN

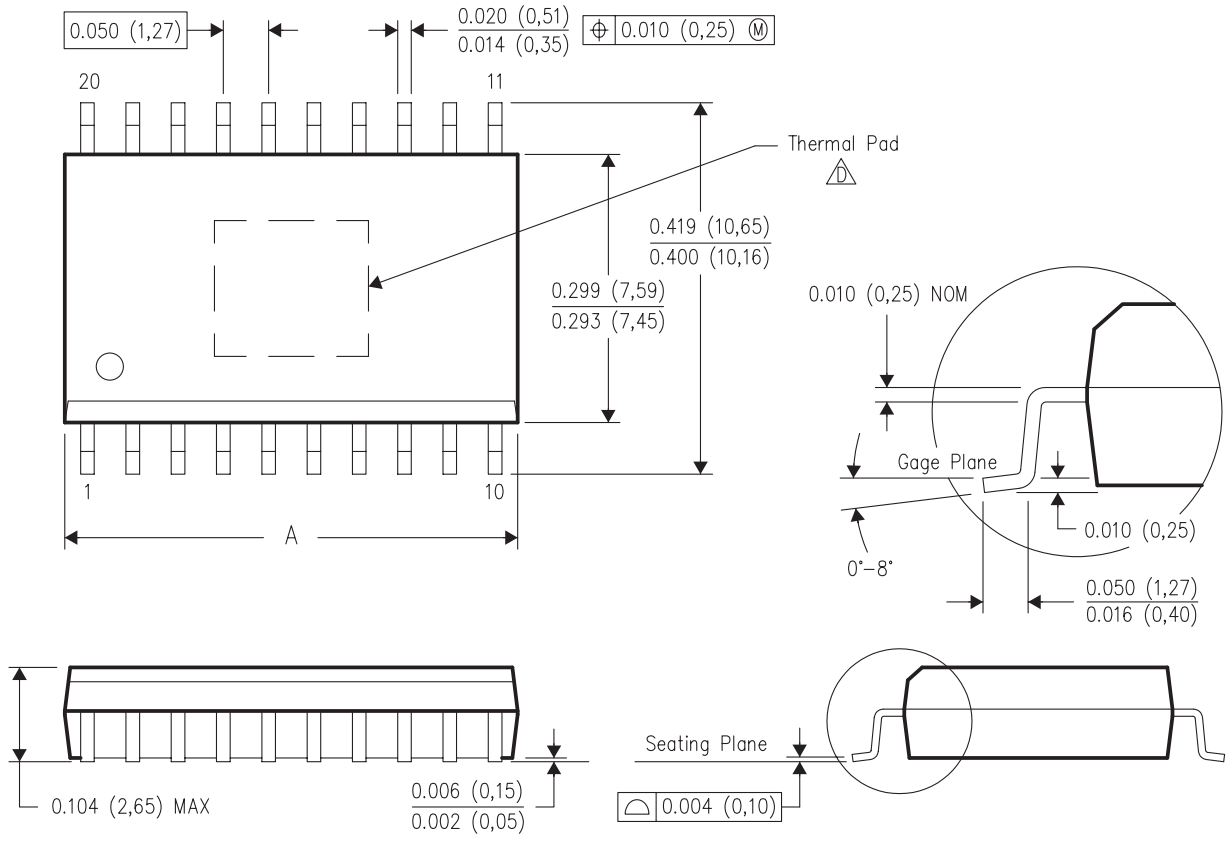


DIM \ PINS **		16	20
A	MIN	———	0.914 (23,22)
	MAX	0.780 (19,80)	0.975 (24,77)
B	MIN	———	0.930 (23,62)
	MAX	———	1.000 (25,40)
C	MIN	0.240 (6,10)	0.260 (6,61)
	MAX	0.260 (6,60)	0.280 (7,11)

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001 (16 pin only)

DWP (R–PDSO–G**) PowerPAD™ PLASTIC SMALL–OUTLINE PACKAGE

20 PINS SHOWN



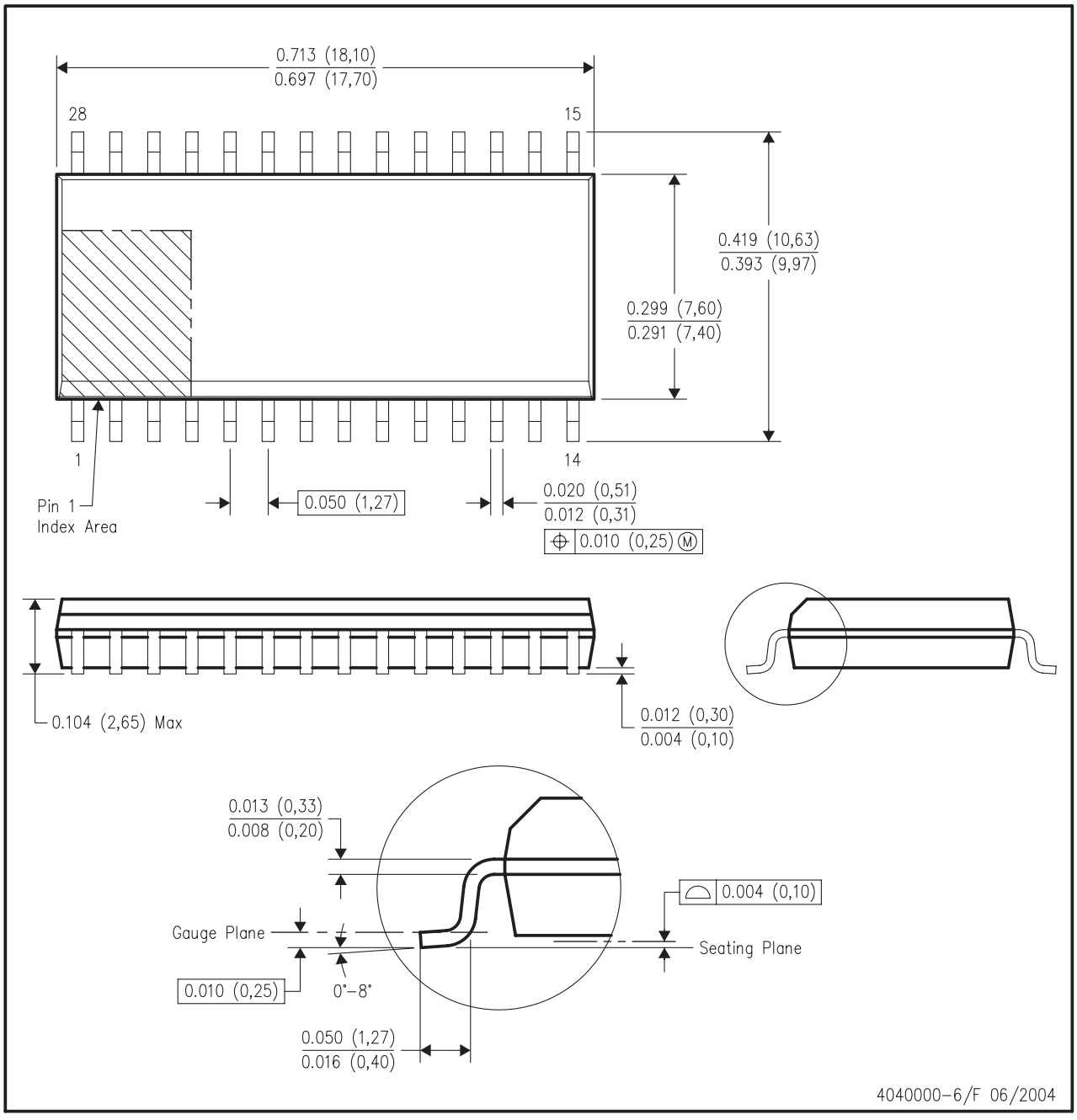
DIM \ PINS **	16	20	24	28
A MAX	0.410 (10,41)	0.510 (12,95)	0.610 (15,49)	0.710 (18,03)
A MIN	0.400 (10,16)	0.500 (12,70)	0.600 (15,24)	0.700 (17,78)

4147575/C 02/05

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
See the product data sheet for details regarding the exposed thermal pad dimensions.

PowerPAD is a trademark of Texas Instruments.

DW (R–PDSO–G28) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AE.

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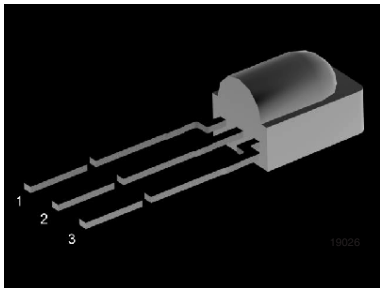
Post Office Box 655303 Dallas, Texas 75265

IR Receiver Modules for Remote Control Systems



FEATURES

- Very low supply current
- Photo detector and preamplifier in one package
- Internal filter for PCM frequency
- Improved shielding against EMI
- Supply voltage: 2.5 V to 5.5 V
- Improved immunity against ambient light
- Insensitive to supply voltage ripple and noise
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC

Pb-free

e3

RoHS COMPLIANT

MECHANICAL DATA

Pinning:

1 = OUT, 2 = GND, 3 = V_S

DESCRIPTION

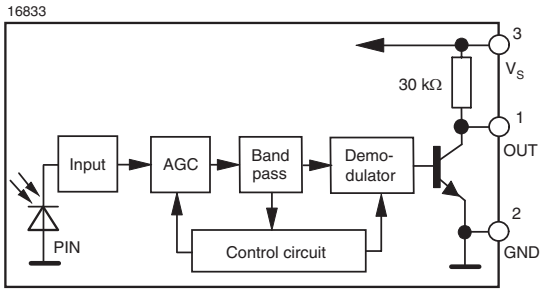
The TSOP382.., TSOP384.. series are miniaturized receivers for infrared remote control systems. A PIN diode and a preamplifier are assembled on a lead frame, the epoxy package acts as an IR filter.

The demodulated output signal can be directly decoded by a microprocessor. The TSOP382.. is compatible with all common IR remote control data formats. The TSOP384.. is optimized to suppress almost all spurious pulses from energy saving fluorescent lamps but will also suppress some data signals.

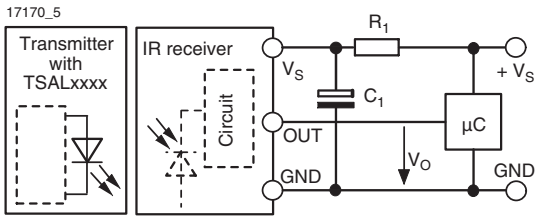
This component has not been qualified according to automotive specifications.

PARTS TABLE		
CARRIER FREQUENCY	STANDARD APPLICATIONS (AGC2/AGC8)	VERY NOISY ENVIRONMENTS (AGC4)
30 kHz	TSOP38230	TSOP38430
33 kHz	TSOP38233	TSOP38433
36 kHz	TSOP38236	TSOP38436
38 kHz	TSOP38238	TSOP38438
40 kHz	TSOP38240	TSOP38440
56 kHz	TSOP38256	TSOP38456

BLOCK DIAGRAM



APPLICATION CIRCUIT



R_1 and C_1 are recommended for protection against EOS. Components should be in the range of 33 Ω < R_1 < 1 kΩ, C_1 > 0.1 µF.

ABSOLUTE MAXIMUM RATINGS (1)				
PARAMETER	**TEST CONDITION**	**SYMBOL**	**VALUE**	**UNIT**
Supply voltage (pin 3)		V_S	- 0.3 to + 6.0	V
Supply current (pin 3)		I_S	3	mA
Output voltage (pin 1)		V_O	- 0.3 to (V_S + 0.3)	V
Output current (pin 1)		I_O	5	mA
Junction temperature		T_j	100	°C
Storage temperature range		T_{stg}	- 25 to + 85	°C
Operating temperature range		T_{amb}	- 25 to + 85	°C
Power consumption	$T_{amb} \leq 85$ °C	P_{tot}	10	mW
Soldering temperature	t ≤ 10 s, 1 mm from case	T_{sd}	260	°C

Note

(1) Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating condtions for extended periods may affect the device reliability.

ELECTRICAL AND OPTICAL CHARACTERISTICS (1)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Supply current (pin 3)	E_v = 0, V_S = 3.3 V	I_{SD}	0.27	0.35	0.45	mA
	E_v = 40 klx, sunlight	I_{SH}		0.45		mA
Supply voltage		V_S	2.5		5.5	V
Transmission distance	E_v = 0, test signal see fig. 1, IR diode TSAL6200, I_F = 250 mA	d		45		m
Output voltage low (pin 1)	I_{OSL} = 0.5 mA, E_e = 0.7 mW/m², test signal see fig. 1	V_{OSL}			100	mV
Minimum irradiance	Pulse width tolerance: $t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o$, test signal see fig. 1	$E_{e\ min.}$		0.15	0.35	mW/m²
Maximum irradiance	$t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o$, test signal see fig. 1	$E_{e\ max.}$	30			W/m²
Directivity	Angle of half transmission distance	$\varphi_{1/2}$		± 45		deg

Note

(1) T_{amb} = 25 °C, unless otherwise specified

TYPICAL CHARACTERISTICS

T_{amb} = 25 °C, unless otherwise specified

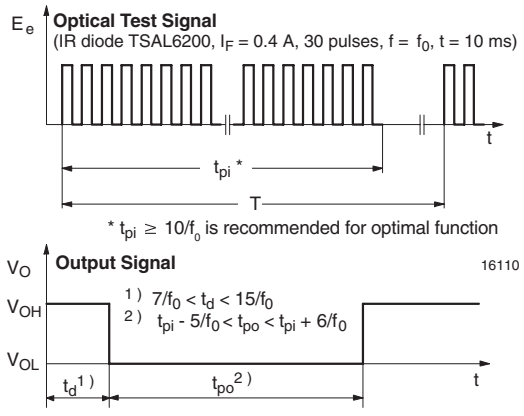


Fig. 1 - Output Active Low

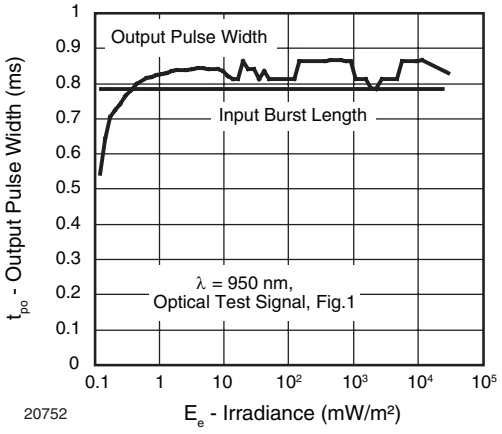


Fig. 2 - Pulse Length and Sensitivity in Dark Ambient

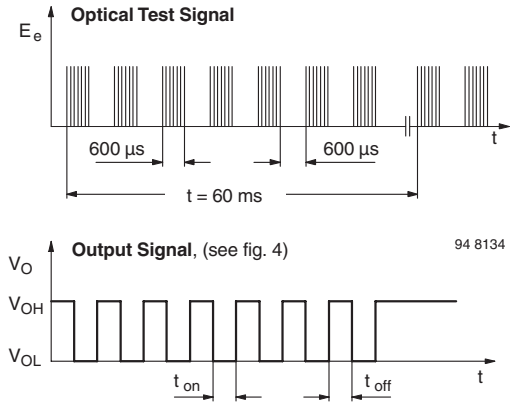


Fig. 3 - Output Function

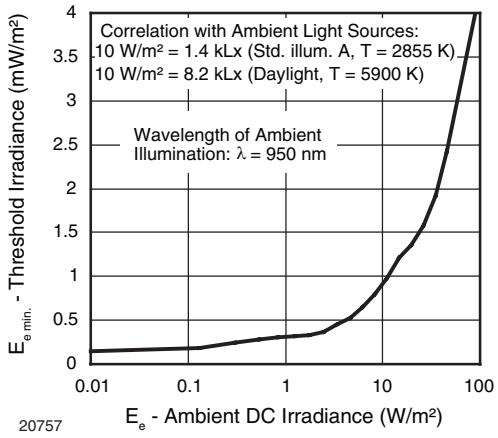


Fig. 6 - Sensitivity in Bright Ambient

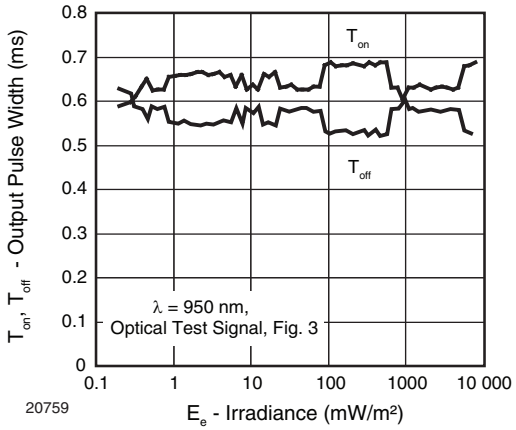


Fig. 4 - Output Pulse Diagram

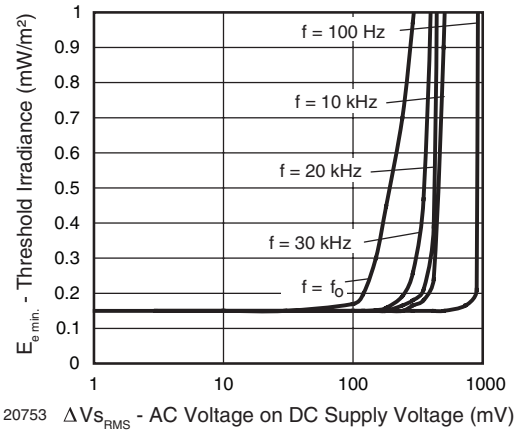


Fig. 7 - Sensitivity vs. Supply Voltage Disturbances

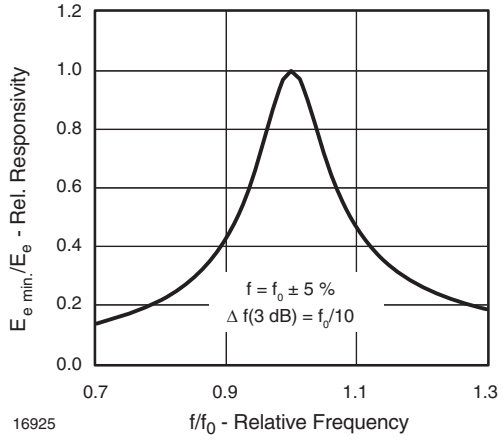


Fig. 5 - Frequency Dependence of Responsivity

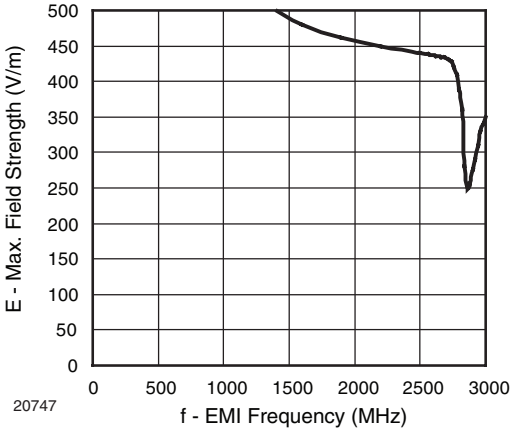


Fig. 8 - Sensitivity vs. Electric Field Disturbances

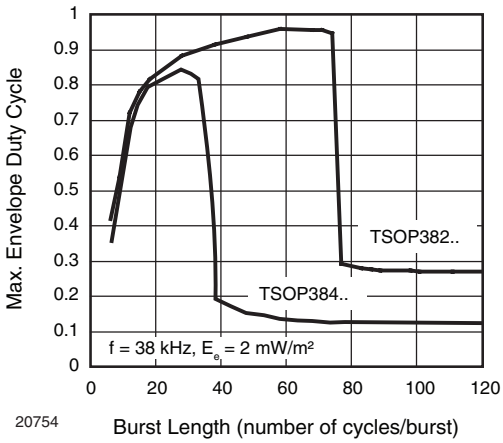


Fig. 9 - Max. Envelope Duty Cycle vs. Burst Length

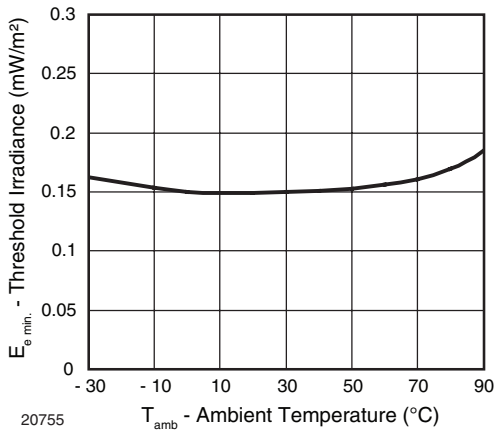


Fig. 10 - Sensitivity vs. Ambient Temperature

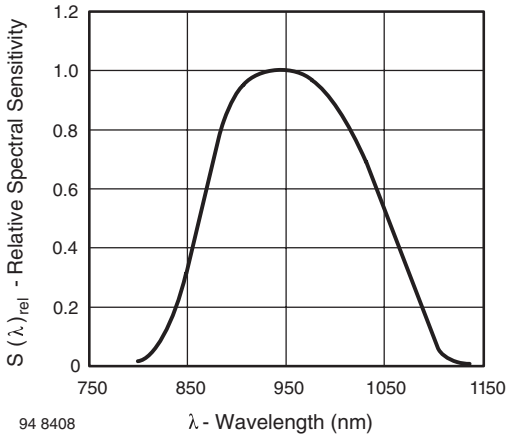


Fig. 11 - Relative Spectral Sensitivity vs. Wavelength

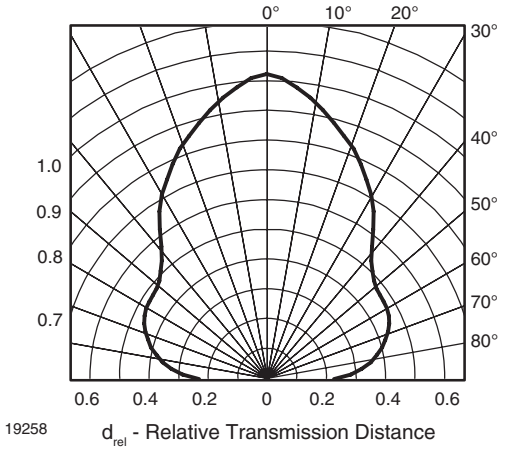


Fig. 12 - Horizontal Directivity

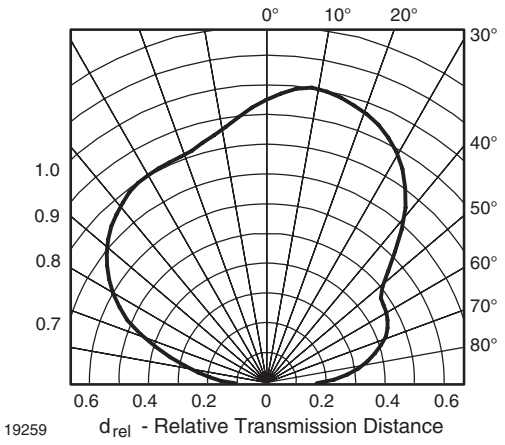


Fig. 13 - Vertical Directivity

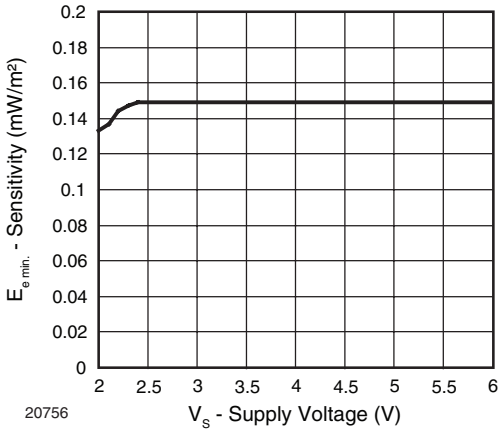


Fig. 14 - Sensitivity vs. Supply Voltage

SUITABLE DATA FORMAT

The TSOP382.., TSOP384.. series are designed to suppress spurious output pulses due to noise or disturbance signals. Data and disturbance signals can be distinguished by the devices according to carrier frequency, burst length and envelope duty cycle. The data signal should be close to the band-pass center frequency (e.g. 38 kHz) and fulfill the conditions in the table below.
When a data signal is applied to the TSOP382.., TSOP384.. in the presence of a disturbance signal, the sensitivity of the receiver is reduced to insure that no spurious pulses are present at the output. Some examples of disturbance signals which are suppressed are:

- DC light (e.g. from tungsten bulb or sunlight)
- Continuous signals at any frequency
- Strongly or weakly modulated noise from fluorescent lamps with electronic ballasts (see figure 15 or figure 16)

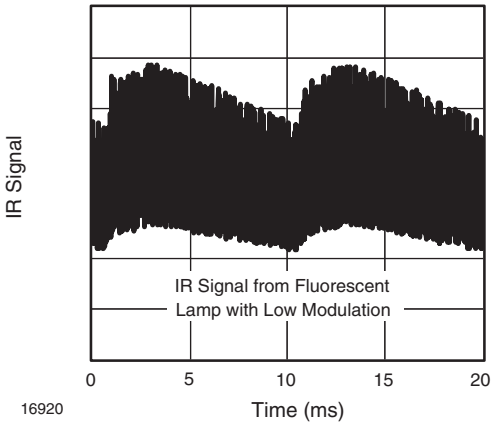


Fig. 15 - IR Signal from Fluorescent Lamp with Low Modulation

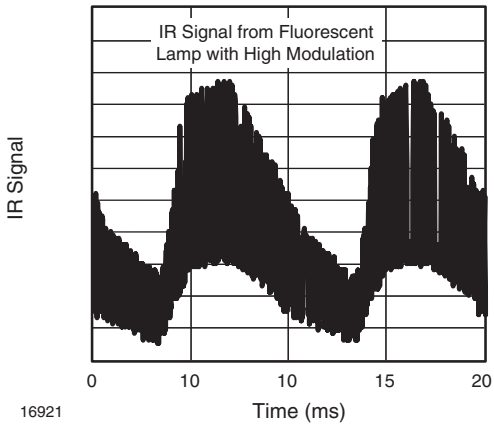
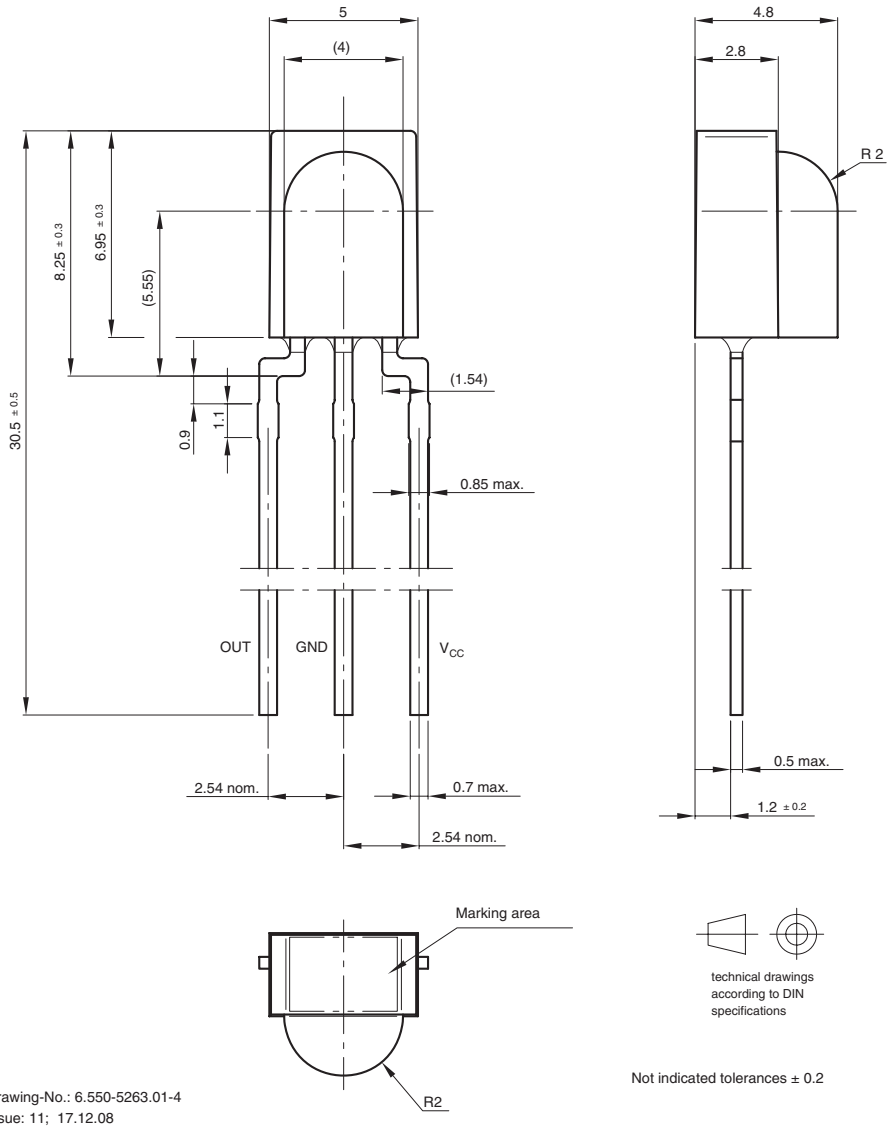


Fig. 16 - IR Signal from Fluorescent Lamp with High Modulation

	TSOP382..	TSOP384..
Minimum burst length	10 cycles/burst	10 cycles/burst
After each burst of length a minimum gap time is required of	10 to 70 cycles ≥ 10 cycles	10 to 35 cycles ≥ 10 cycles
For bursts greater than a minimum gap time in the data stream is needed of	70 cycles > 4 x burst length	35 cycles > 10 x burst length
Maximum number of continuous short bursts/second	1800	1500
Recommended for NEC code	yes	yes
Recommended for RC5/RC6 code	yes	yes
Recommended for Sony code	yes	no
Recommended for Thomson 56 kHz code	yes	yes
Recommended for Mitsubishi code (38 kHz, preburst 8 ms, 16 bit)	yes	no
Recommended for Sharp code	yes	yes
Suppression of interference from fluorescent lamps	Most common disturbance signals are suppressed	Even extreme disturbance signals are suppressed

Note
For data formats with short bursts please see the datasheet for TSOP381.., TSOP383..

PACKAGE DIMENSIONS in millimeters



Drawing-No.: 6.550-5263.01-4
Issue: 11; 17.12.08
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